Text

Defect Text(s)...

Seq #: 1.000

Ins/Rev: 28-NOV-2016/28-NOV-2016 By: KERR, C.B. (20009338) QMRB

The supplier identified an escapement on OCU 1F67700-1 S/N 0034 while reviewing subassembly pictures for an unrelated purpose.

Several inductors on the 1F67750-1 CMS circuit card, S/N 0079, had epoxy fillets, but did not have the strap of epoxy applied to them. Reference the attached photo of the card.

Engineering Req. Text(s)...

Seq #: 1.000

Ins/Rev: 28-NOV-2016/28-NOV-2016 By: KERR, C.B. (20009338) QMRB

Per Dwg 1F67750 Zone A28 and Flag Note 31, "Fillet and single strap bond per STP1008-02 using STM1013-02" for L200-L208.

Disposition Text(s)...

Seq #: 0.100 INFO

Ins/Rev: 28-NOV-2016/ By: KERR, C.B. (20009338) QMRB

Hardware is to remain in the MRC until a disposition decision has been reached. The hardware will be controlled through use of a QS-814-1 "Withheld" label. Okay to continue operations that are not affected by this defect.

Seq #: 0.500 INFO

Ins/Rev: 28-NOV-2016/ By: KERR, C.B. (20009338) QMRB

Note: The QASS-SS-001 Appendix A checklist is not required for this work. Reference QS408.

The complexity, level of intrusiveness, uniqueness, or opportunity for problems associated with this work and/or process does not warrant the additional process controls/scrutiny provided by the checklist.

Seq #: 0.900 INFO

Ins/Rev: 28-NOV-2016/ By: KERR, C.B. (20009338) QMRB

This PIRS document will be routed to CRE/EMRB/Engineering for evaluation and disposition.

Seq #: 1.000 INFO

Ins/Rev: 30-NOV-2016/ By: KERR, C.B. (20009338) QMRB

The supplier is to perform a test in order to determine if this condition is acceptable to use as-is.

As directed by CRE Peter Van Der Hoop:

The strap bond is added to ensure the part is adequately held in place. The sleeved parts tend to lead to weak fillet bonds since the sleeve does not adhere to the 2216 very well and can tear. To build confidence in the shipped unit we would like to run a test to show the fillet bond is adequate to hold the small part in place. Below is a proposed test to gather some data:

1.Using a scrap PWB (does not need to be CMS card and long as there is a large enough area stake a ferrite bead on solder mask only)
2.Attach a sleeved ferrite bead to the PWB
  a.Clean the board prior to installing the bead
  b.Ensure the installation follows the OCU requirement for the fillet to go beyond the sleeve and onto the ferrite bead
  c.Do not add a strap bond to the test part
  d.Follow all OCU curing requirement
3.Loop a wire or string through the bead. The loop needs to be large enough and strong enough to attach a force gauge
4.Use a force gauge to determine the required force to pull the ferrite bead off the

PWB
5.Document the failure mode that allowed the part to pull off

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End of report